

ABSTRACT OF THE DISCLOSURE

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A circuit board which ^{includes} ~~comprises~~ a conductive pattern section 4 with a pattern formed on a conductive layer 3, provided on a board main body 2, wherein two or more bonding positions 6a, 6b, 6c that bumps of a part mounted by ultrasonic bonding strike are set in the conductive pattern section 4, characterized in that a notch part 8a, or a recess extending from the margin of the conductive pattern section 4 to the inside thereof and reaching the proximity of the a bonding position, or an isolated notch part 8b ~~or recess~~ is formed in the conductive layer ³ ₁ in the proximity of ~~at least~~ a one bonding position ^x corresponding to the position of connection of a part by ultrasonic bonding.

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